

REMARKS

This application has been carefully reviewed in light of the Office Action dated August 26, 2004. Claims 3, 5 to 9, and 11 to 13 are in the application, of which Claims 3 and 6 are the independent. Claim 3 has been amended herein. Reconsideration and further examination are respectfully requested.

Applicant notes with appreciation that Claims 6 to 9 and 11 to 13 have been allowed. These claims have not been amended herein, and thus remain in condition for allowance.

Claims 3 to 5 were rejected under 35 U.S.C. § 102(b) over U.S. Patent No. 6,059,188 (diFazio). The rejection is respectfully traversed.

According to one feature of the invention as recited by Claim 3, the first substrate is cut at a position where the spacer is disposed under the first substrate.

diFazio is not seen to teach or suggest at least the foregoing feature.

As shown in diFazio's Fig. 4B, the upper substrate 181 is cut at a position outside of the position where the spacer 182 is disposed. The spacer 182 is not disposed under the edge of the upper substrate 181.

According to another feature of the invention as recited by Claim 3, the spacer is disposed inwards of the electrode pad after the cutting step is effected.

diFazio also is not seen to teach or suggest this feature.

As shown in diFazio's Fig. 4B, the spacer 182 is not disposed inwards of the interconnect pad 188.

The dependent claims are also submitted to be patentable because they set forth additional aspects of the present invention and are dependent from the independent claim discussed above. Therefore, separate and individual consideration of each dependent claim is respectfully requested.

An Information Disclosure Statement was submitted on October 6, 2004, and consideration of the documents cited therein is respectfully requested. In this regard, Fig. 4 of U.S. Patent No. 5,981,945 (Spaeth), which is one of the documents cited in the Information Disclosure Statement, shows a plate 18 cut by a sawing cut 13 located between two spacers 7. However, as shown in that figure, plate 18 is not cut at a position where the spacer 7 is disposed under the plate 18.

No other matters being raised, it is believed that the entire application is fully in condition for allowance, and such action is courteously solicited.

Applicant's undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

  
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